

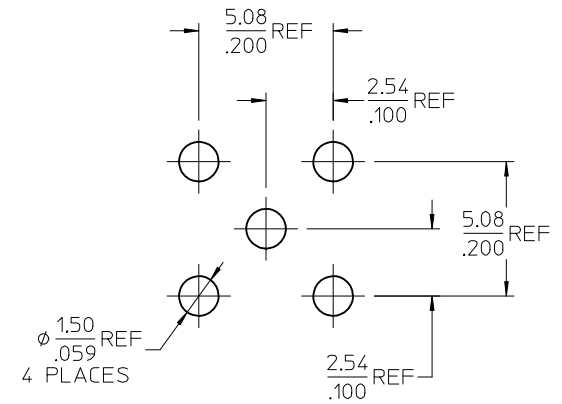
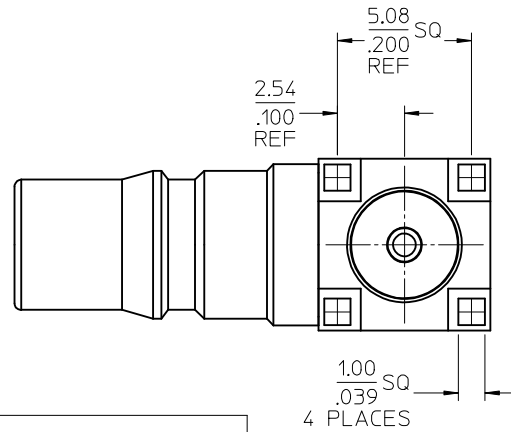
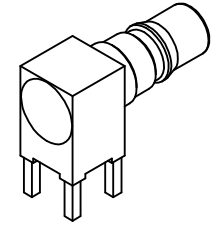
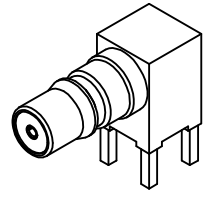
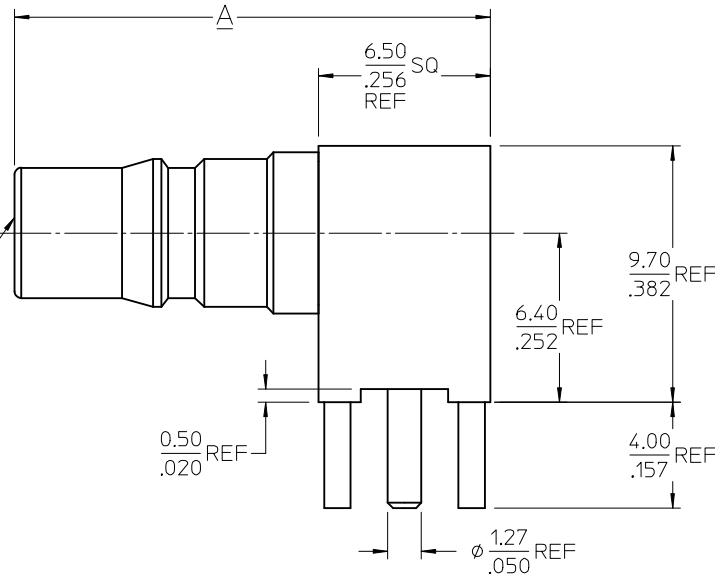
MATERIALS AND FINISHES

BODY, CAP BRASS  
 PLATED GOLD (10 MICROINCHES MIN)  
 OVER CHEMICAL NICKEL

INSULATOR TEFLON

CENTER CONTACT BERYLLIUM COPPER  
 PLATED GOLD (10 MICROINCHES MIN)  
 OVER CHEMICAL NICKEL

QMA JACK  
 INTERFACE



RECOMMENDED PCB  
 LAYOUT

73254-0242	21.00/.827 REF	BAG
73254-0241	18.00/.709 REF	P/N 73254-0240, ONE PER BAG
73254-0240	18.00/.709 REF	TRAY
PART NO.	DIM A	PACKAGING

CHG:	UPDATE PACKAGING	2015/05/27	DESCRIPTION	2015/05/29
	FOR -0240 & -0242			
EC NO:	URF2015-0665			
DRWR:	RYEH			
CHKD:				
APPR:	YCHENG			
REV	A4			

QUALITY SYMBOLS	▽=0
	▽=0
▽=0	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± .005	± .0005
3 PLACES ± .005	± .0005
2 PLACES ± .005	± .0005
1 PLACE ± .005	± .0005
0 PLACE ± .005	± .0005
ANGULAR ± 2 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	MM/IN	SCALE	7:1	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION
DRAWN BY	SSS	DATE	2005/02/08	QMA JACK, R/A, PCB 50 OHMS, EWR2710 QMA-J/PCB		
CHECKED BY	TEF	DATE	2005/02/08			
APPROVED BY	JDW	DATE	2005/02/08			
MATERIAL NO.	SEE TABLE	DOCUMENT NO.	SD-73254-024	SHEET NO. 1 OF 1		
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